

MEC1-130-02-L-D-EM2

MEC1-120-02-L-D-RA1-SL

MEC1-120-02-F-D-EM2

(1,00 mm) .0394"

MEC1-RA, MEC1-EM SERIES

# RIGHT ANGLE/EDGE MOUNT SOCKETS

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC1-RA](http://www.samtec.com?MEC1-RA)

**Insulator Material:** Black LCP

**Contact Material:** Phosphor Bronze

**Plating:** Au or Sn over 50µ" (1,27 µm) Ni

**Current Rating:** 1.6 A per pin

(2 adjacent pins powered)

**Operating Temp Range:** -55°C to +125°C

**Insertion Depth:** (5,84 mm) .230" to (8,13 mm) .320"

**RoHS Compliant:** Yes

**Processing:** Lead-Free Solderable: Yes

**SMT Lead Coplanarity:** (0,10 mm) .004" max (05-40)

(0,15 mm) .006" max (50-70)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



**MEC1** - **1** POSITIONS PER ROW - **CARD SLOT** - **PLATING OPTION** - **D** - **RA1** - **NP** - **SL**

Mates with: (1,60 mm) .062" card

05, 08, 20, 30, 40, 50, 60, 70

-02 = (1,60 mm) .062" thick card

-F = Gold flash on contact, Matte Tin on tail

-L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

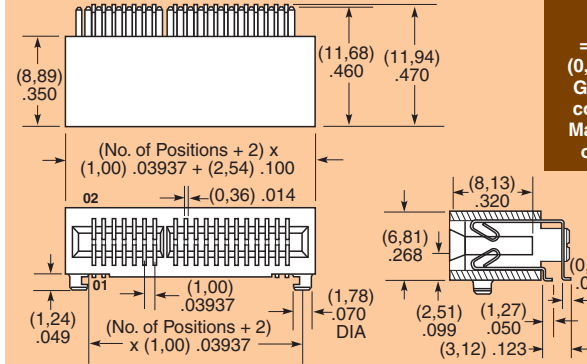
POSITIONS PER ROW	POLARIZED POSITIONS
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
50	41, 42
60	31, 32, 63 & 64
70	53, 54, 115 & 116

-NP = No Polarization (8 positions only) Leave Blank for polarization

ALSO AVAILABLE (MOQ Required)

- Elevated body height
- Other platings Contact Samtec.

**Note:** While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.



**Note:** Some sizes, styles and options are non-standard, non-returnable.

MEC1-RA 6,81 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	4.5 GHz / 9 Gbps
Differential Pair Signaling	5.5 GHz / 11 Gbps

\*Performance data includes effects of a non-optimized PCB. Complete test data available at [www.samtec.com?MEC1-RA](http://www.samtec.com?MEC1-RA) or contact sig@samtec.com

## APPLICATION

Samtec recommends that pads on the mating board be Gold plated.

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC1-EM](http://www.samtec.com?MEC1-EM)

**Insulator Material:** Black LCP

**Contact Material:** Phosphor Bronze

**Plating:** Au or Sn over 50µ" (1,27 µm) Ni

**Current Rating:** 1.8 A per pin

(2 adjacent pins powered)

**Operating Temp Range:** -55°C to +125°C

**Insertion Depth:** (5,84 mm) .230" to (8,13 mm) .320"

**RoHS Compliant:** Yes

**Lead-Free Solderable:** Yes

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



**MEC1** - **1** POSITIONS PER ROW - **02** - **PLATING OPTION** - **D** - **EM2** - **NP**

Mates with: (1,60 mm) .062" card

05, 08, 20, 30, 40, 50, 60, 70

-F = Gold flash on contact, Matte Tin on tail

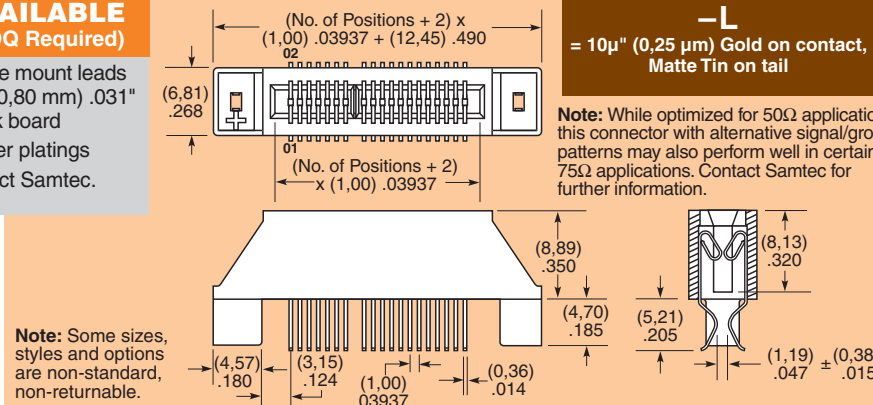
-L = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail

-NP = No Polarization (8 positions only) Leave Blank for polarization

ALSO AVAILABLE (MOQ Required)

- Edge mount leads for (0,80 mm) .031" thick board
- Other platings Contact Samtec.

**Note:** While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.



**Note:** Some sizes, styles and options are non-standard, non-returnable.

POSITIONS PER ROW	POLARIZED POSITIONS
05	3, 4
08	5, 6
20	15, 16
30	21, 22
40	31, 32
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60	31, 32, 63 & 64
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Due to technical progress, all designs, specifications and components are subject to change without notice.

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